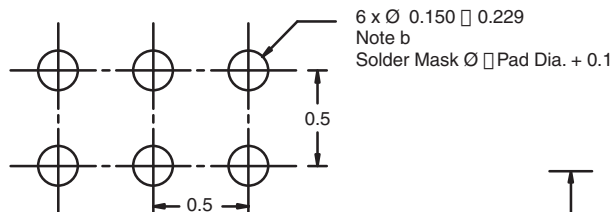
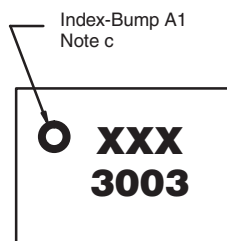


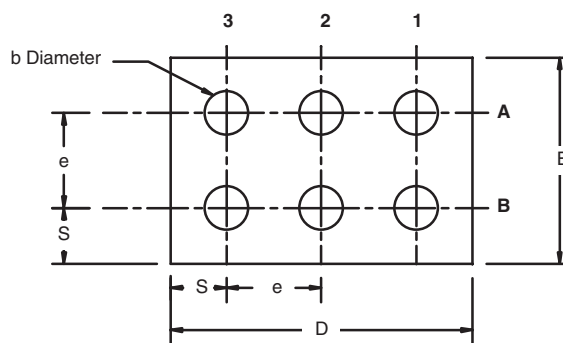
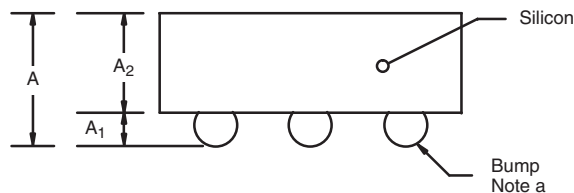
MICRO FOOT: 6-BUMP (3 mm x 2 mm, 0.5 mm PITCH, 165 µm BUMP HEIGHT)



Recommended Land Pattern



Top Side (Die Back)



Notes

(unless otherwise specified)

- Bump is Eutectic 63/57 Sn/Pb or lead (Pb)-free Sn/Ag/Cu.
- Non-solder mask defined copper landing pad.
- Laser mark on silicon die back; no coating. Shown is not actual marking; sample only.

EUTECTIC (Sn/Pb)				
DIM.	MILLIMETERS ^a		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.610	0.685	0.0240	0.0270
A ₁	0.140	0.190	0.0055	0.0075
A ₂	0.470	0.495	0.0185	0.0195
b	0.180	0.250	0.0071	0.0098
D	1.490	1.515	0.0587	0.0596
E	0.990	1.015	0.0390	0.0400
e	0.5 BASIC		0.0197 BASIC	
S	0.245	0.258	0.0096	0.0101

Note

- Use millimeters as the primary measurement.

LEAD (Pb)-FREE (Sn/Ag/Cu)				
DIM.	MILLIMETERS ^a		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.688	0.753	0.0271	0.0296
A ₁	0.218	0.258	0.0086	0.0102
A ₂	0.470	0.495	0.0185	0.0195
b	0.306	0.346	0.0120	0.0136
D	1.490	1.515	0.0587	0.0596
E	0.990	1.015	0.0390	0.0400
e	0.5 BASIC		0.0197 BASIC	
S	0.245	0.258	0.0096	0.0101

Note

- Use millimeters as the primary measurement.

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